

Material Content Data Sheet

RoHS | Halogen-Free

Sales Product Name	ESD8V0L2B-03L E6327	**Issued**	29. August 2013
MA#	MA000251707		
Package	PG-TSLP-3-1	**Weight***	0.55 mg

Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.001	0.16		1649	
	noble metal	gold	7440-57-5	0.004	0.64		6394	
	inorganic material	silicon	7440-21-3	0.043	7.80	8.60	78040	86083
leadframe	non noble metal	nickel	7440-02-0	0.071	12.96	12.96	129582	129582
wire	noble metal	gold	7440-57-5	0.011	2.08	2.08	20828	20828
encapsulation	organic material	carbon black	1333-86-4	0.004	0.74		7355	
	plastics	epoxy resin	-	0.055	9.93		99286	
	inorganic material	silicondioxide	60676-86-0	0.346	62.89	73.56	628812	735453
leadfinish	noble metal	gold	7440-57-5	0.008	1.40	1.40	14027	14027
plating	noble metal	gold	7440-57-5	0.008	1.40	1.40	14027	14027
*deviation	< 10%				Sum in total:	100,00		1000000

Important Remarks:

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